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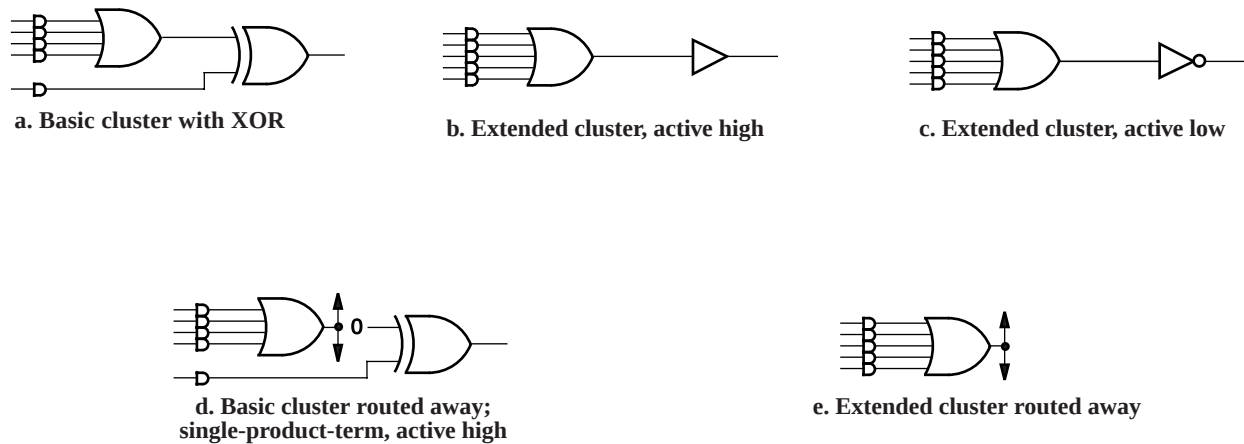
Understanding [Embedded - CPLDs \(Complex Programmable Logic Devices\)](#)

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

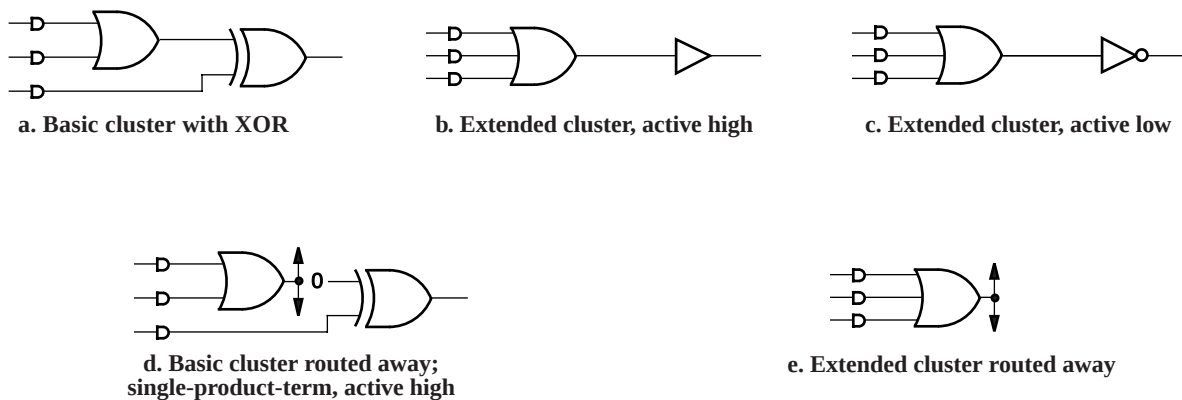
Details

Product Status	Not For New Designs
Programmable Type	In System Programmable
Delay Time tpd(1) Max	7.5 ns
Voltage Supply - Internal	4.5V ~ 5.5V
Number of Logic Elements/Blocks	-
Number of Macrocells	128
Number of Gates	-
Number of I/O	64
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	100-BQFP
Supplier Device Package	100-PQFP (14x20)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/m4a5-128-64-7yni



17466G-007

Figure 3. Logic Allocator Configurations: Synchronous Mode



17466G-008

Figure 4. Logic Allocator Configurations: Asynchronous Mode

Note that the configuration of the logic allocator has absolutely no impact on the speed of the signal. All configurations have the same delay. This means that designers do not have to decide between optimizing resources or speed; both can be optimized.

If not used in the cluster, the extra product term can act in conjunction with the basic cluster to provide XOR logic for such functions as data comparison, or it can work with the D-,T-type flip-flop to provide for J-K, and S-R register operation. In addition, if the basic cluster is routed to another macrocell, the extra product term is still available for logic. In this case, the first XOR input will be a logic 0. This circuit has the flexibility to route product terms elsewhere without giving up the use of the macrocell.

Product term clusters do not “wrap” around a PAL block. This means that the macrocells at the ends of the block have fewer product terms available.

Output Switch Matrix

The output switch matrix allows macrocells to be connected to any of several I/O cells within a PAL block. This provides high flexibility in determining pinout and allows design changes to occur without effecting pinout.

In ispMACH 4A devices with 2:1 Macrocell-I/O cell ratio, each PAL block has twice as many macrocells as I/O cells. The ispMACH 4A output switch matrix allows for half of the macrocells to drive I/O cells within a PAL block, in combinations according to Figure 9. Each I/O cell can choose from eight macrocells; each macrocell has a choice of four I/O cells. The ispMACH 4A devices with 1:1 Macrocell-I/O cell ratio allow each macrocell to drive one of eight I/O cells (Figure 9).

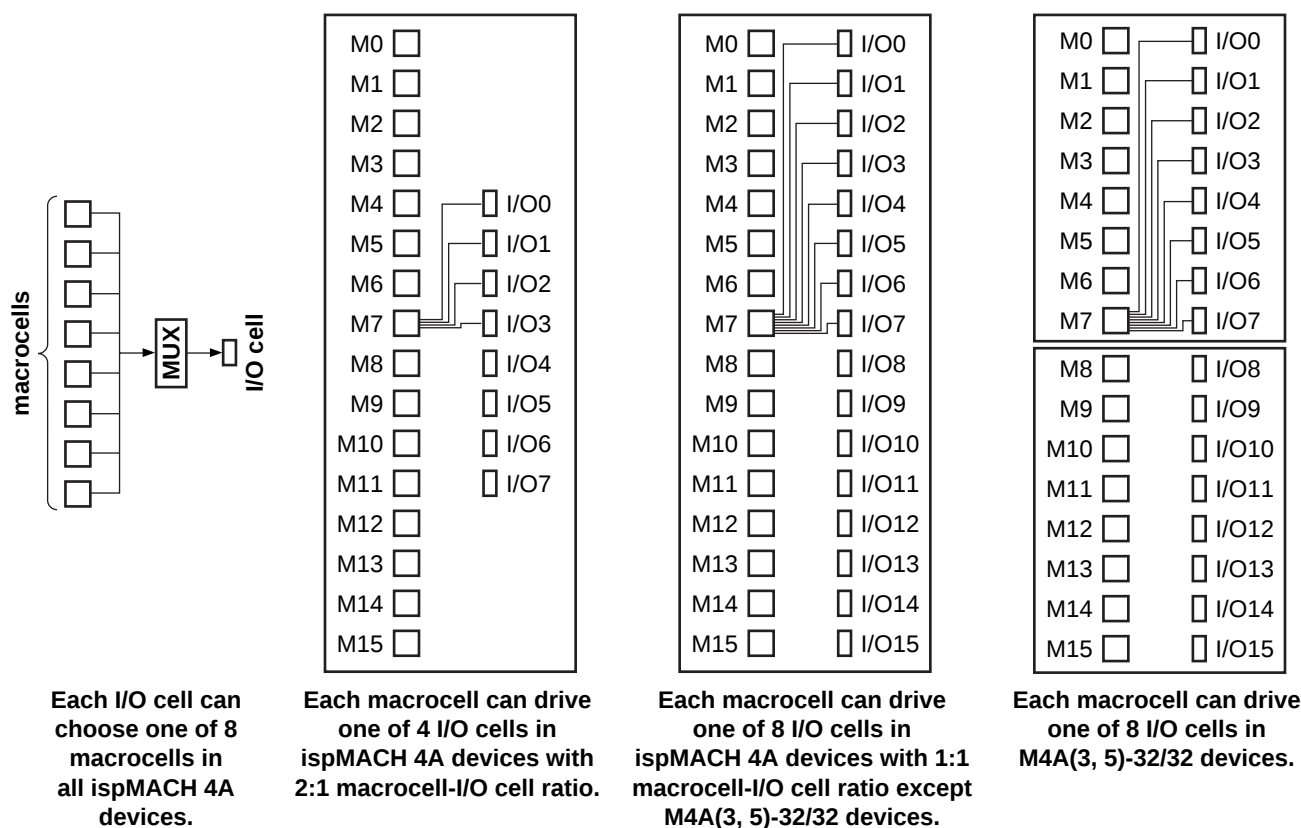


Figure 9. ispMACH 4A Output Switch Matrix

Table 10. Output Switch Matrix Combinations for ispMACH 4A Devices with 2:1 Macrocell-I/O Cell Ratio

Macrocell	Routeable to I/O Cells
M0, M1	I/O0, I/O5, I/O6, I/O7
M2, M3	I/O0, I/O1, I/O6, I/O7
M4, M5	I/O0, I/O1, I/O2, I/O7
M6, M7	I/O0, I/O1, I/O2, I/O3
M8, M9	I/O1, I/O2, I/O3, I/O4
M10, M11	I/O2, I/O3, I/O4, I/O5

Table 10. Output Switch Matrix Combinations for ispMACH 4A Devices with 2:1 Macrocell-I/O Cell Ratio

Macrocell	Routable to I/O Cells
M12, M13	I/O3, I/O4, I/O5, I/O6
M14, M15	I/O4, I/O5, I/O6, I/O7

I/O Cell	Available Macrocells
I/O0	M0, M1, M2, M3, M4, M5, M6, M7
I/O1	M2, M3, M4, M5, M6, M7, M8, M9
I/O2	M4, M5, M6, M7, M8, M9, M10, M11
I/O3	M6, M7, M8, M9, M10, M11, M12, M13
I/O4	M8, M9, M10, M11, M12, M13, M14, M15
I/O5	M0, M1, M10, M11, M12, M13, M14, M15
I/O6	M0, M1, M2, M3, M12, M13, M14, M15
I/O7	M0, M1, M2, M3, M4, M5, M14, M15

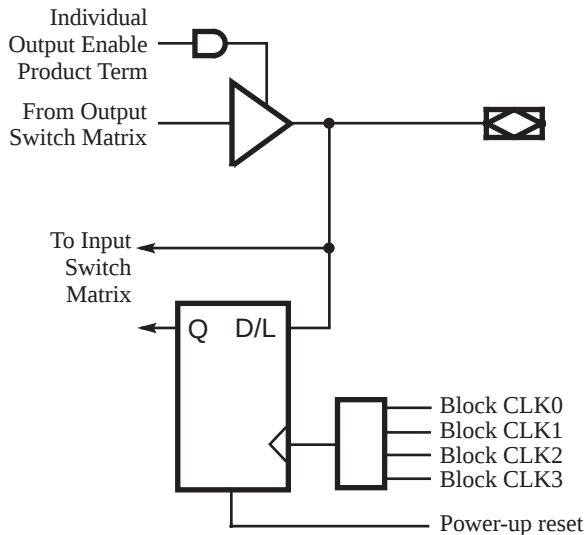
Table 11. Output Switch Matrix Combinations for M4A3-256/160 and M4A3-256/192

Macrocell	Routable to I/O Cells							
M0	I/O0	I/O1	I/O2	I/O3	I/O4	I/O5	I/O6	I/O7
M1	I/O0	I/O1	I/O2	I/O3	I/O4	I/O5	I/O6	I/O7
M2	I/O0	I/O1	I/O2	I/O3	I/O4	I/O5	I/O6	I/O7
M3	I/O0	I/O1	I/O2	I/O3	I/O4	I/O5	I/O6	I/O7
M4	I/O0	I/O1	I/O2	I/O3	I/O4	I/O5	I/O6	I/O7
M5	I/O0	I/O1	I/O2	I/O3	I/O4	I/O5	I/O6	I/O7
M6	I/O0	I/O1	I/O2	I/O3	I/O4	I/O5	I/O6	I/O7
M7	I/O0	I/O1	I/O2	I/O3	I/O4	I/O5	I/O6	I/O7
M8	I/O8	I/O9	I/O10	I/O11	I/O12	I/O13	I/O14	I/O15
M9	I/O8	I/O9	I/O10	I/O11	I/O12	I/O13	I/O14	I/O15
M10	I/O8	I/O9	I/O10	I/O11	I/O12	I/O13	I/O14	I/O15
M11	I/O8	I/O9	I/O10	I/O11	I/O12	I/O13	I/O14	I/O15
M12	I/O8	I/O9	I/O10	I/O11	I/O12	I/O13	I/O14	I/O15
M13	I/O8	I/O9	I/O10	I/O11	I/O12	I/O13	I/O14	I/O15
M14	I/O8	I/O9	I/O10	I/O11	I/O12	I/O13	I/O14	I/O15
M15	I/O8	I/O9	I/O10	I/O11	I/O12	I/O13	I/O14	I/O15

I/O Cell	Available Macrocells							
I/O0	M0	M1	M2	M3	M4	M5	M6	M7
I/O1	M0	M1	M2	M3	M4	M5	M6	M7
I/O2	M0	M1	M2	M3	M4	M5	M6	M7
I/O3	M0	M1	M2	M3	M4	M5	M6	M7
I/O4	M0	M1	M2	M3	M4	M5	M6	M7
I/O5	M0	M1	M2	M3	M4	M5	M6	M7
I/O6	M0	M1	M2	M3	M4	M5	M6	M7
I/O7	M0	M1	M2	M3	M4	M5	M6	M7

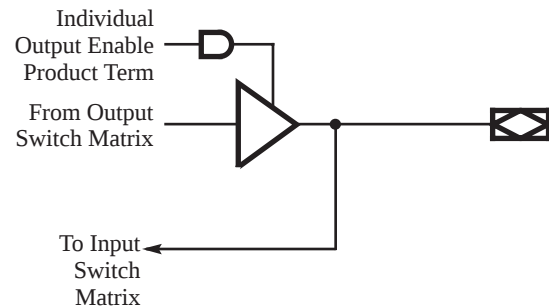
I/O Cell

The I/O cell (Figures 10 and 11) simply consists of a programmable output enable, a feedback path, and flip-flop (except ispMACH 4A devices with 1:1 macrocell-I/O cell ratio). An individual output enable product term is provided for each I/O cell. The feedback signal drives the input switch matrix.



17466G-017

Figure 10. I/O Cell for ispMACH 4A Devices with 2:1 Macrocell-I/O Cell Ratio



17466G-018

Figure 11. I/O Cell for ispMACH 4A Devices with 1:1 Macrocell-I/O Cell Ratio

The I/O cell (Figure 10) contains a flip-flop, which provides the capability for storing the input in a D-type register or latch. The clock can be any of the PAL block clocks. Both the direct and registered versions of the input are sent to the input switch matrix. This allows for such functions as “time-domain-multiplexed” data comparison, where the first data value is stored, and then the second data value is put on the I/O pin and compared with the previous stored value.

Note that the flip-flop used in the ispMACH 4A I/O cell is independent of the flip-flops in the macrocells. It powers up to a logic low.

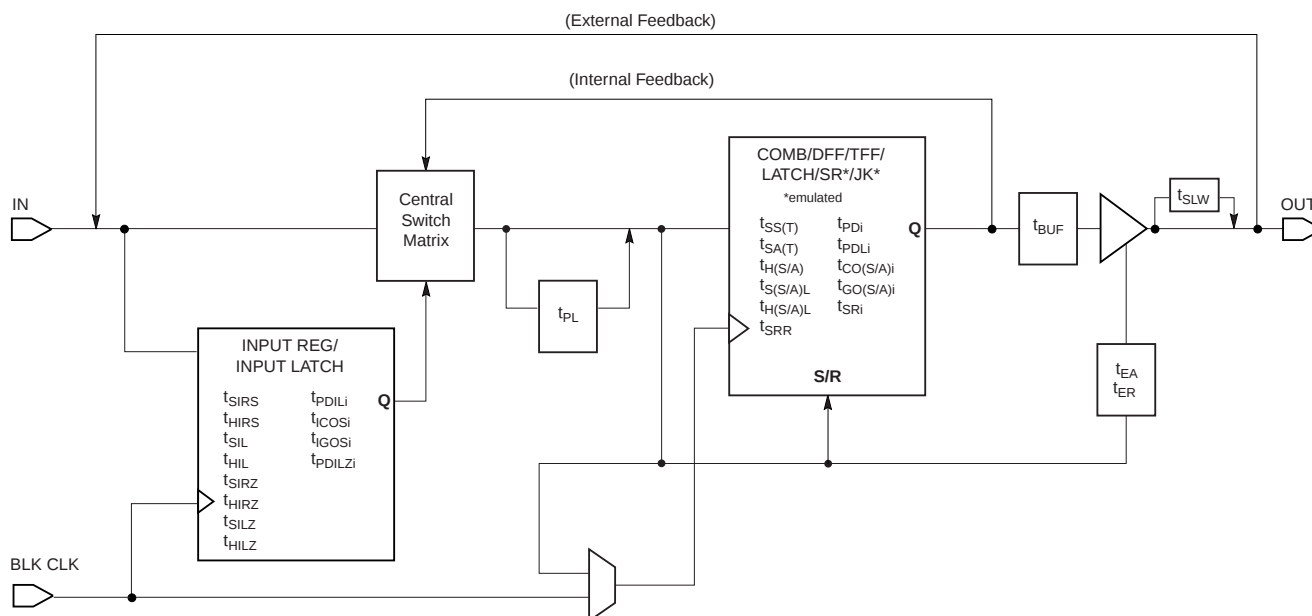
Zero-Hold-Time Input Register

The ispMACH 4A devices have a zero-hold-time (ZHT) fuse which controls the time delay associated with loading data into all I/O cell registers and latches. When programmed, the ZHT fuse increases the data path setup delays to input storage elements, matching equivalent delays in the clock path. When the fuse is erased, the setup time to the input storage element is minimized. This feature facilitates doing worst-case designs for which data is loaded from sources which have low (or zero) minimum output propagation delays from clock edges.

ispMACH 4A TIMING MODEL

The primary focus of the ispMACH 4A timing model is to accurately represent the timing in a ispMACH 4A device, and at the same time, be easy to understand. This model accurately describes all combinatorial and registered paths through the device, making a distinction between internal feedback and external feedback. A signal uses internal feedback when it is fed back into the switch matrix or block without having to go through the output buffer. The input register specifications are also reported as internal feedback. When a signal is fed back into the switch matrix after having gone through the output buffer, it is using external feedback.

The parameter, t_{BUF} , is defined as the time it takes to go from feedback through the output buffer to the I/O pad. If a signal goes to the internal feedback rather than to the I/O pad, the parameter designator is followed by an “i”. By adding t_{BUF} to this internal parameter, the external parameter is derived. For example, $t_{PD} = t_{PDi} + t_{BUF}$. A diagram representing the modularized ispMACH 4A timing model is shown in Figure 15. Refer to the application note entitled *MACH 4 Timing and High Speed Design* for a more detailed discussion about the timing parameters.



17466G-025

Figure 15. ispMACH 4A Timing Model

SPEEDLOCKING FOR GUARANTEED FIXED TIMING

The ispMACH 4A architecture allows allocation of up to 20 product terms to an individual macrocell with the assistance of an XOR gate without incurring additional timing delays.

The design of the switch matrix and PAL blocks guarantee a fixed pin-to-pin delay that is independent of the logic required by the design. Other competitive CPLDs incur serious timing delays as product terms expand beyond their typical 4 or 5 product term limits. Speed and SpeedLocking combine to give designs easy access to the performance required in today's designs.

weakly pulled up. For the circuit diagram, please refer to the document entitled *MACH Endurance Characteristics* on the Lattice Data Book CD-ROM or Lattice web site.

POWER MANAGEMENT

Each individual PAL block in ispMACH 4A devices features a programmable low-power mode, which results in power savings of up to 50%. The signal speed paths in the low-power PAL block will be slower than those in the non-low-power PAL block. This feature allows speed critical paths to run at maximum frequency while the rest of the signal paths operate in the low-power mode.

PROGRAMMABLE SLEW RATE

Each ispMACH 4A device I/O has an individually programmable output slew rate control bit. Each output can be individually configured for the higher speed transition (3 V/ns) or for the lower noise transition (1 V/ns). For high-speed designs with long, unterminated traces, the slow-slew rate will introduce fewer reflections, less noise, and keep ground bounce to a minimum. For designs with short traces or well terminated lines, the fast slew rate can be used to achieve the highest speed. The slew rate is adjusted independent of power.

POWER-UP RESET/SET

All flip-flops power up to a known state for predictable system initialization. If a macrocell is configured to SET on a signal from the control generator, then that macrocell will be SET during device power-up. If a macrocell is configured to RESET on a signal from the control generator or is not configured for set/reset, then that macrocell will RESET on power-up. To guarantee initialization values, the V_{CC} rise must be monotonic, and the clock must be inactive until the reset delay time has elapsed.

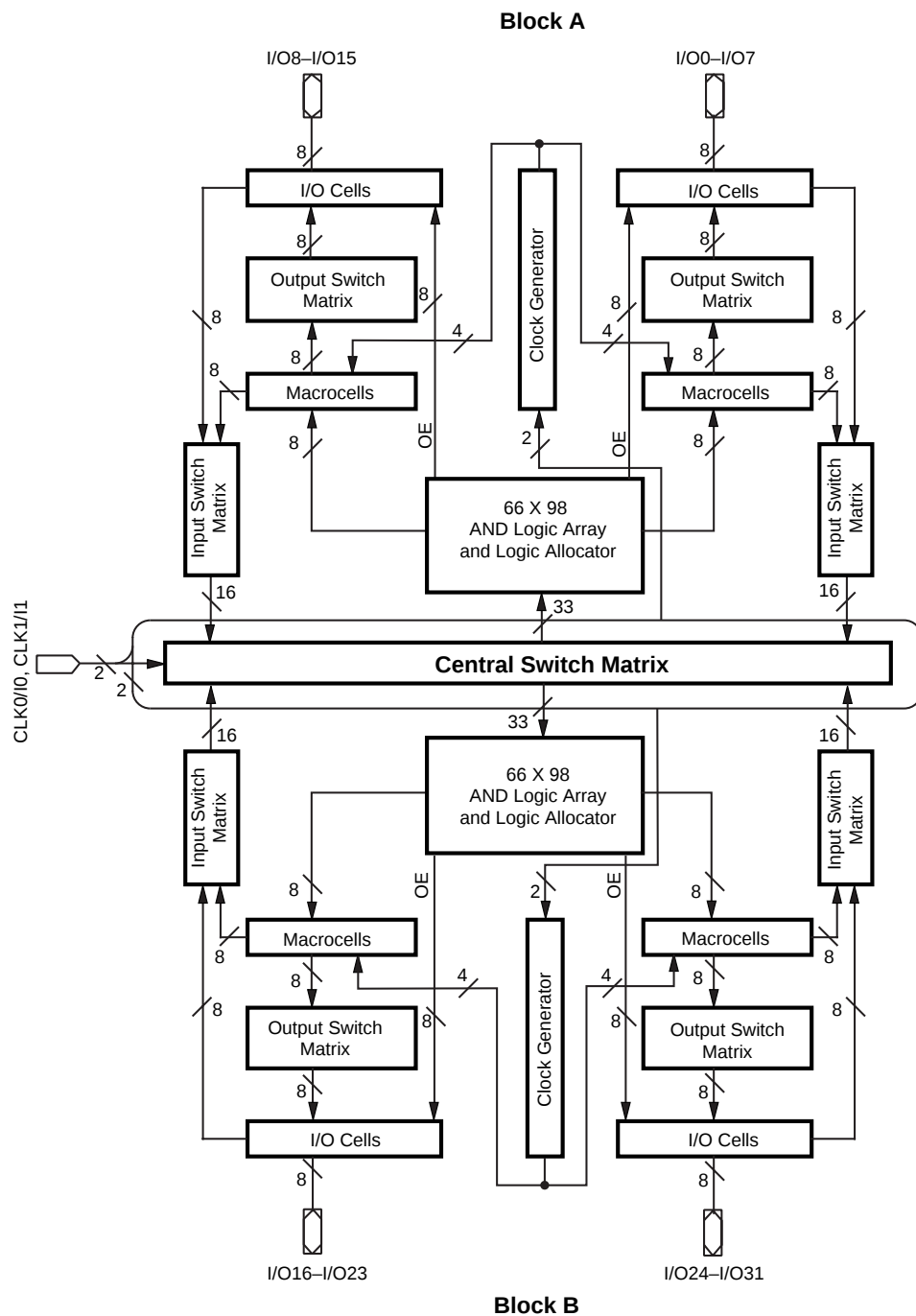
SECURITY BIT

A programmable security bit is provided on the ispMACH 4A devices as a deterrent to unauthorized copying of the array configuration patterns. Once programmed, this bit defeats readback of the programmed pattern by a device programmer, securing proprietary designs from competitors. Programming and verification are also defeated by the security bit. The bit can only be reset by erasing the entire device.

HOT SOCKETING

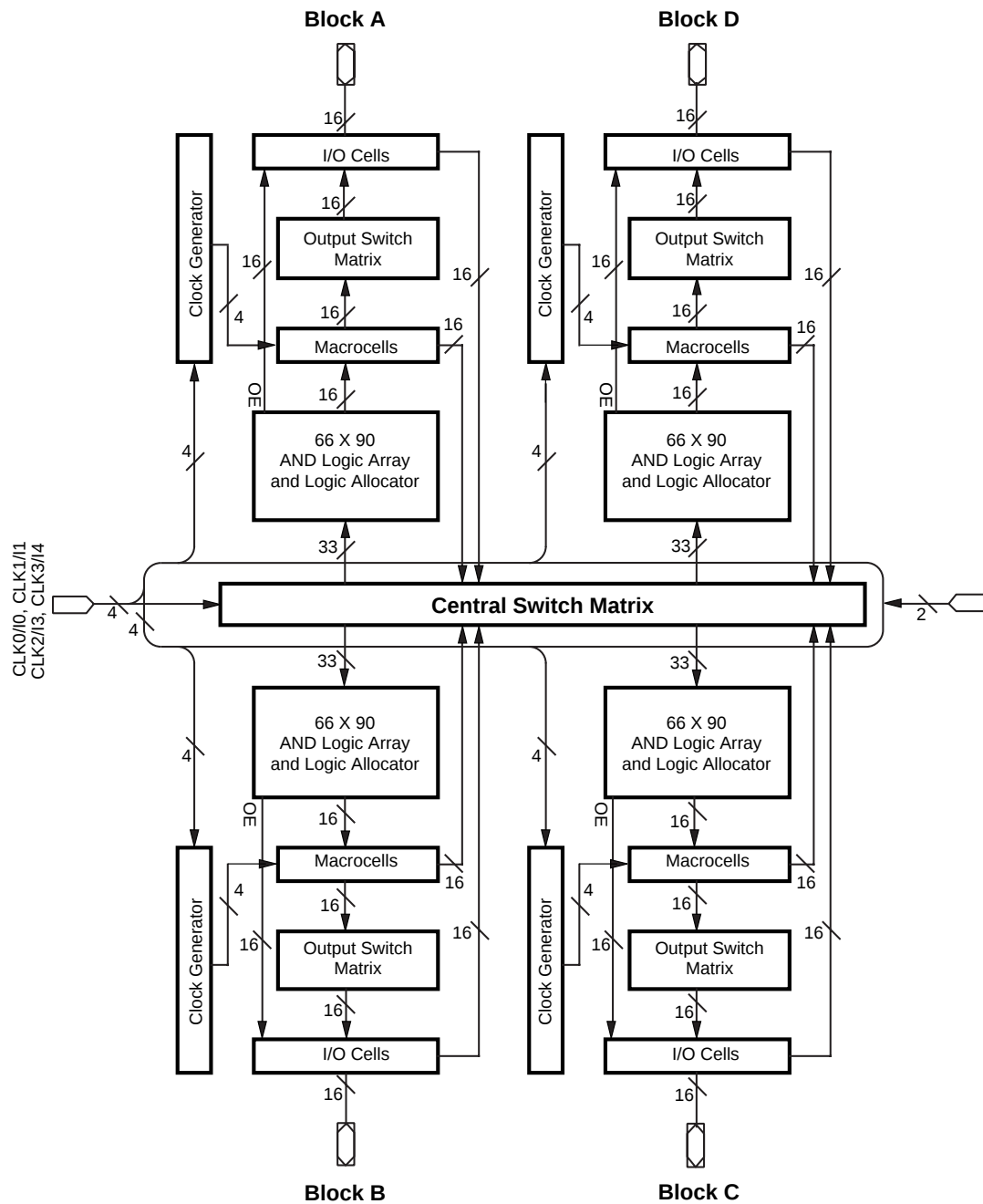
ispMACH 4A devices are well-suited for those applications that require hot socketing capability. Hot socketing a device requires that the device, when powered down, can tolerate active signals on the I/Os and inputs without being damaged. Additionally, it requires that the effects of the powered-down MACH devices be minimal on active signals.

BLOCK DIAGRAM – M4A(3,5)-32/32



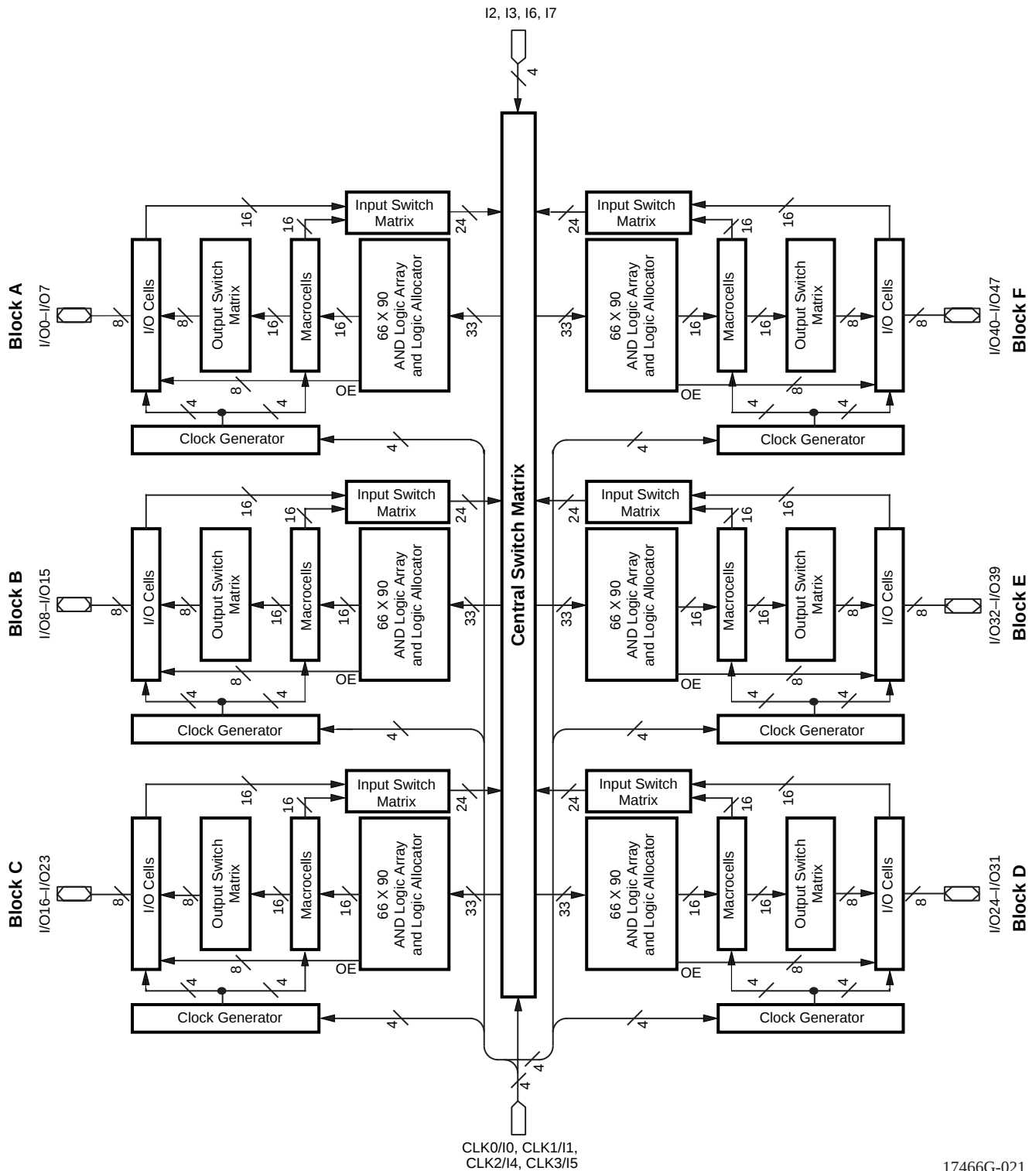
17466H-019

BLOCK DIAGRAM – M4A3-64/64



17466H-020A

BLOCK DIAGRAM – M4A(3,5)-96/48



17466G-021

ABSOLUTE MAXIMUM RATINGS

M4A5

Storage Temperature. -65°C to +150°C
 Ambient Temperature
 with Power Applied. -55°C to +100°C
 Device Junction Temperature. +130°C
 Supply Voltage
 with Respect to Ground -0.5 V to +7.0 V
 DC Input Voltage -0.5 V to $V_{CC} + 0.5$ V
 Static Discharge Voltage 2000 V
 Latchup Current ($T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$) 200 mA

Stresses above those listed under Absolute Maximum Ratings may cause permanent device failure. Functionality at or above these limits is not implied. Exposure to Absolute Maximum Ratings for extended periods may affect device reliability.

OPERATING RANGES

Commercial (C) Devices

Ambient Temperature (T_A)
 Operating in Free Air. 0°C to $+70^\circ\text{C}$
 Supply Voltage (V_{CC})
 with Respect to Ground. +4.75 V to +5.25 V

Industrial (I) Devices

Ambient Temperature (T_A)
 Operating in Free Air. -40°C to $+85^\circ\text{C}$
 Supply Voltage (V_{CC})
 with Respect to Ground. +4.50 V to +5.5 V
Operating ranges define those limits between which the functionality of the device is guaranteed.

5-V DC CHARACTERISTICS OVER OPERATING RANGES

Parameter Symbol	Parameter Description	Test Conditions	Min	Typ	Max	Unit
V_{OH}	Output HIGH Voltage	$I_{OH} = -3.2$ mA, $V_{CC} = \text{Min}$, $V_{IN} = V_{IH}$ or V_{IL}	2.4			V
		$I_{OH} = -100$ μA , $V_{CC} = \text{Max}$, $V_{IN} = V_{IH}$ or V_{IL}		3.3	3.6	V
V_{OL}	Output LOW Voltage	$I_{OL} = 24$ mA, $V_{CC} = \text{Min}$, $V_{IN} = V_{IH}$ or V_{IL} (Note 1)			0.5	V
V_{IH}	Input HIGH Voltage	Guaranteed Input Logical HIGH Voltage for all Inputs (Note 2)	2.0			V
V_{IL}	Input LOW Voltage	Guaranteed Input Logical LOW Voltage for all Inputs (Note 2)			0.8	V
I_{IH}	Input HIGH Leakage Current	$V_{IN} = 5.25$ V, $V_{CC} = \text{Max}$ (Note 3)			10	μA
I_{IL}	Input LOW Leakage Current	$V_{IN} = 0$ V, $V_{CC} = \text{Max}$ (Note 3)			-10	μA
I_{OZH}	Off-State Output Leakage Current HIGH	$V_{OUT} = 5.25$ V, $V_{CC} = \text{Max}$, $V_{IN} = V_{IH}$ or V_{IL} (Note 3)			10	μA
I_{OZL}	Off-State Output Leakage Current LOW	$V_{OUT} = 0$ V, $V_{CC} = \text{Max}$, $V_{IN} = V_{IH}$ or V_{IL} (Note 3)			-10	μA
I_{SC}	Output Short-Circuit Current	$V_{OUT} = 0.5$ V, $V_{CC} = \text{Max}$ (Note 4)	-30		-160	mA

Notes:

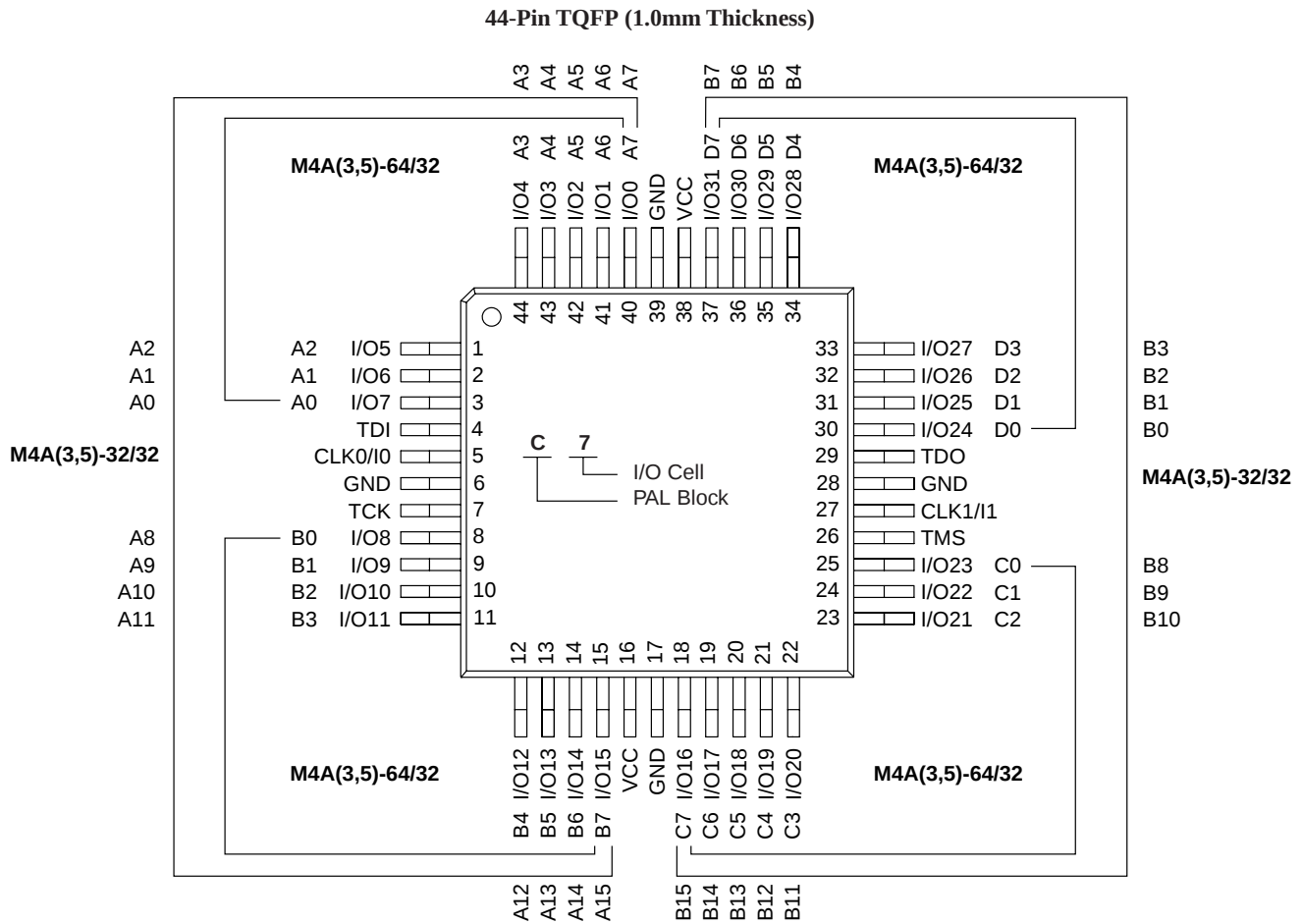
1. Total I_{OL} for one PAL block should not exceed 64 mA.
2. These are absolute values with respect to device ground, and all overshoots due to system or tester noise are included.
3. I/O pin leakage is the worst case of I_{IL} and I_{OZL} (or I_{IH} and I_{OZH}).
4. Not more than one output should be shorted at a time and duration of the short-circuit should not exceed one second.
 $V_{OUT} = 0.5$ V has been chosen to avoid test problems caused by tester ground degradation.

ispMACH 4A TIMING PARAMETERS OVER OPERATING RANGES¹

		-5		-55		-6		-65		-7		-10		-12		-14		Unit
		Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
Input Register Delays with ZHT Option:																		
t _{SIRZ}	Input register setup time - ZHT	6.0		6.0		6.0		6.0		6.0		6.0		6.0		6.0		ns
t _{HIRZ}	Input register hold time - ZHT	0.0		0.0		0.0		0.0		0.0		0.0		0.0		0.0		ns
Input Latch Delays with ZHT Option:																		
t _{SILZ}	Input latch setup time - ZHT	6.0		6.0		6.0		6.0		6.0		6.0		6.0		6.0		ns
t _{HILZ}	Input latch hold time - ZHT	0.0		0.0		0.0		0.0		0.0		0.0		0.0		0.0		ns
t _{PDIL} Z _i	Transparent input latch to internal feedback - ZHT		6.0		6.0		6.0		6.0		6.0		6.0		6.0		6.0	ns
Output Delays:																		
t _{BUF}	Output buffer delay		1.5		1.5		1.8		2.0		2.5		3.0		3.0		3.0	ns
t _{SLW}	Slow slew rate delay adder		2.5		2.5		2.5		2.5		2.5		2.5		2.5		2.5	ns
t _{EA}	Output enable time		7.5		7.5		8.5		8.5		9.5		10.0		12.0		15.0	ns
t _{ER}	Output disable time		7.5		7.5		8.5		8.5		9.5		10.0		12.0		15.0	ns
Power Delay:																		
t _{PL}	Power-down mode delay adder		2.5		2.5		2.5		2.5		2.5		2.5		2.5		2.5	ns
Reset and Preset Delays:																		
t _{SRi}	Asynchronous reset or preset to internal register output		7.5		7.7		8.0		8.0		9.5		11.0		13.0		16.0	ns
t _{SR}	Asynchronous reset or preset to register output		9.0		9.2		10.0		10.0		12.0		14.0		16.0		19.0	ns
t _{SRR}	Asynchronous reset and preset register recovery time	7.0		7.0		7.5		7.5		8.0		8.0		10.0		15.0		ns
t _{SRW}	Asynchronous reset or preset width	7.0		7.0		8.0		8.0		10.0		10.0		12.0		15.0		ns
Clock/LE Width:																		
t _{WLS}	Global clock width low	2.0		2.0		2.5		2.5		3.0		4.0		5.0		6.0		ns
t _{WHS}	Global clock width high	2.0		2.0		2.5		2.5		3.0		4.0		5.0		6.0		ns
t _{WLA}	Product term clock width low	3.0		3.0		3.5		3.5		4.0		5.0		8.0		9.0		ns
t _{WHA}	Product term clock width high	3.0		3.0		3.5		3.5		4.0		5.0		8.0		9.0		ns
t _{GWS}	Global gate width low (for low transparent) or high (for high transparent)	4.0		4.0		4.5		4.5		5.0		5.0		6.0		6.0		ns
t _{GWA}	Product term gate width low (for low transparent) or high (for high transparent)	4.0		4.0		4.5		4.5		5.0		5.0		6.0		9.0		ns
t _{WIRL}	Input register clock width low	3.0		3.0		3.5		3.5		4.0		5.0		6.0		6.0		ns
t _{WIRH}	Input register clock width high	3.0		3.0		3.5		3.5		4.0		5.0		6.0		6.0		ns
t _{WIL}	Input latch gate width	4.0		4.0		4.5		4.5		5.0		5.0		6.0		6.0		ns

44-PIN TQFP CONNECTION DIAGRAM (M4A(3,5)-32/32 AND M4A(3,5)-64/32)

Top View



PIN DESIGNATIONS

CLK/I = Clock or Input

GND = Ground

I/O = Input/Output

V_{CC} = Supply Voltage

TDI = Test Data In

TCK = Test Clock

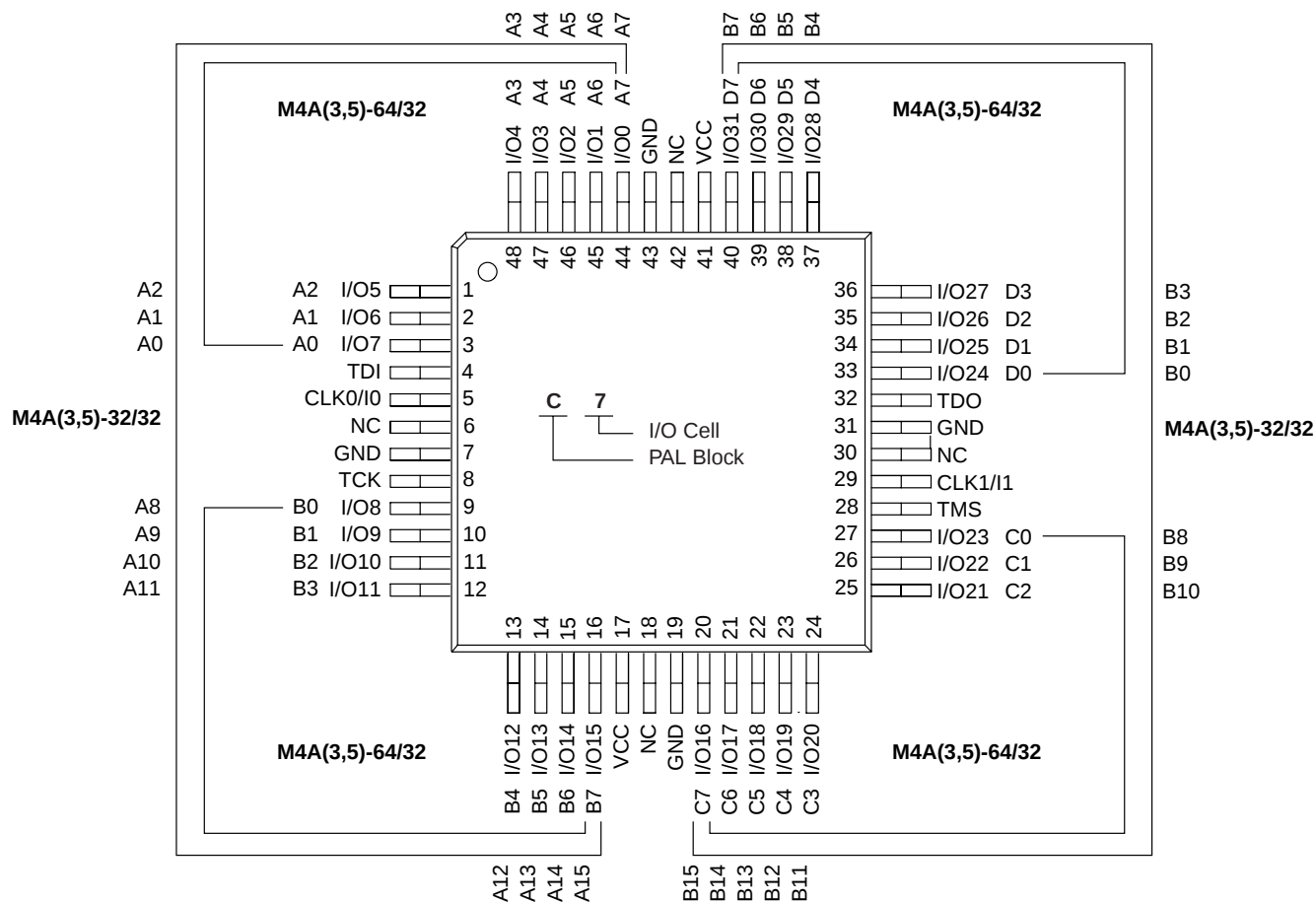
TMS = Test Mode Select

TDO = Test Data Out

48-PIN TQFP CONNECTION DIAGRAM (M4A(3,5)-32/32 AND M4A(3,5)-64/32)

Top View

48-Pin TQFP (1.4mm Thickness)



17466G-028

PIN DESIGNATIONS

CLK/I = Clock or Input

GND = Ground

I/O = Input/Output

V_{CC} = Supply Voltage

NC = No Connect

TDI = Test Data In

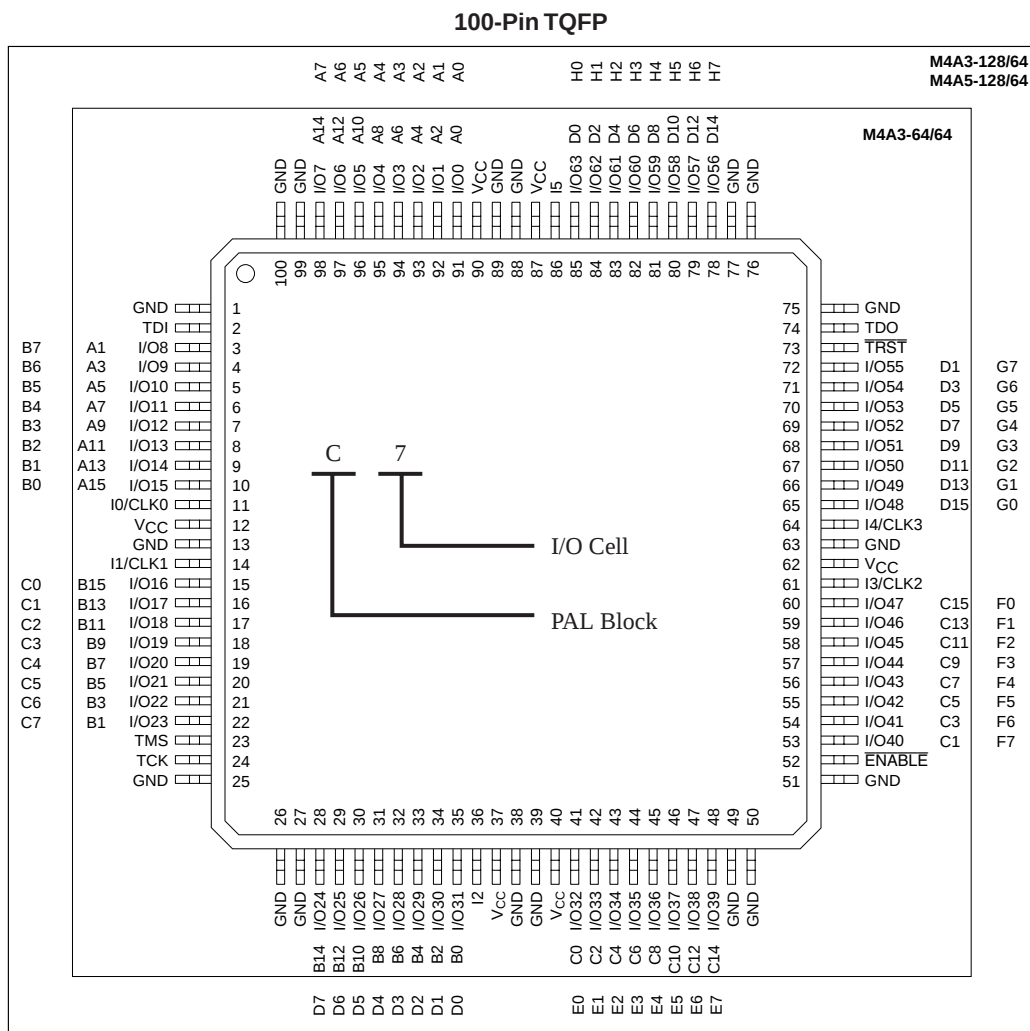
TCK = Test Clock

TMS = Test Mode Select

TDO = Test Data Out

100-PIN TQFP CONNECTION DIAGRAM (M4A3-64/64 AND M4A(3,5)-128/64)

Top View



PIN DESIGNATIONS

CLK/I = Clock or Input

GND = Ground

I = Input

I/O = Input/Output

V_{CC} = Supply Voltage

TDI = Test Data In

TCK = Test Clock

TMS = Test Mode Select

TDO = Test Data Out

TRST = Test Reset

ENABLE = Program

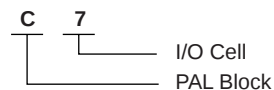
144-BALL FPBGA CONNECTION DIAGRAM (M4A3-192/96)

Bottom View

144-Ball fpBGA													
	12	11	10	9	8	7	6	5	4	3	2	1	
A	GND	I/O72 L7	I/O76 L3	I13	GBCLK3	I0	I/O82 A2	I/O86 A6	I/O88 B0	I/O93 B5	I/O95 B7	GND	A
B	GND	I/O73 L6	I/O77 L2	I/O79 L0	VCC	I1	I/O83 A3	I/O87 A7	I/O90 B2	I/O94 B6	I/O0 D7	TDI	B
C	GND	TD0	I/O74 L5	I14	GND	I/O80 A0	I/O84 A4	GND	I/O92 B4	I/O1 D6	I/O4 D3	I/O3 D4	C
D	I/O67 K4	I/O69 K2	I/O71 K0	I/O75 L4	GBCLK0	I/O81 A1	VCC	I/O91 B3	I/O2 D5	I2	I/O6 D1	I/O7 D0	D
E	I12	I/O64 K7	I/O66 K5	I/O70 K1	I/O78 L1	I/O85 A5	I/O89 B1	I/O5 D2	I/O8 C7	I4	GND	VCC	E
F	I10	I11	GND	I/O65 K6	I/O68 K3	I15	I3	GND	I/O12 C3	I/O11 C4	I/O10 C5	I/O9 C6	F
G	I/O60 J3	I/O61 J2	I/O62 J1	I/O63 J0	VCC	GND	I7	I/O20 E3	I/O17 E6	I/O15 C0	I/O14 C1	I/O13 C2	G
H	I/O56 J7	I/O57 J6	I/O58 J5	I/O59 J4	I/O53 I2	I/O41 H1	I/O37 G5	I/O30 F1	I/O22 E1	I/O18 E5	I/O16 E7	VCC	H
J	I/O55 I0	I/O54 I1	VCC	I/O50 I5	I/O43 H3	VCC	I/O33 G1	GBCLK2	I/O27 F4	I/O23 E0	I/O21 E2	I/O19 E4	J
K	I/O51 I4	I/O52 I3	I/O49 I6	I/O44 H4	GND	I/O36 G4	I/O32 G0	VCC	I6	I/O26 F5	TCK	TMS	K
L	GND	I/O48 I7	I/O46 H6	I/O42 H2	I/O39 G7	I/O35 G3	I9	GND	I/O31 F0	I/O29 F2	I/O25 F6	GND	L
M	GND	I/O47 H7	I/O45 H5	I/O40 H0	I/O38 G6	I/O34 G2	I8	GBCLK1	I5	I/O28 F3	I/O24 F7	GND	M
	12	11	10	9	8	7	6	5	4	3	2	1	

PIN DESIGNATIONS

CLK = Clock
 GND = Ground
 I = Input
 I/O = Input/Output
 N/C = No Connect
 VCC = Supply Voltage
 TDI = Test Data In
 TCK = Test Clock
 TMS = Test Mode Select
 TD0 = Test Data Out

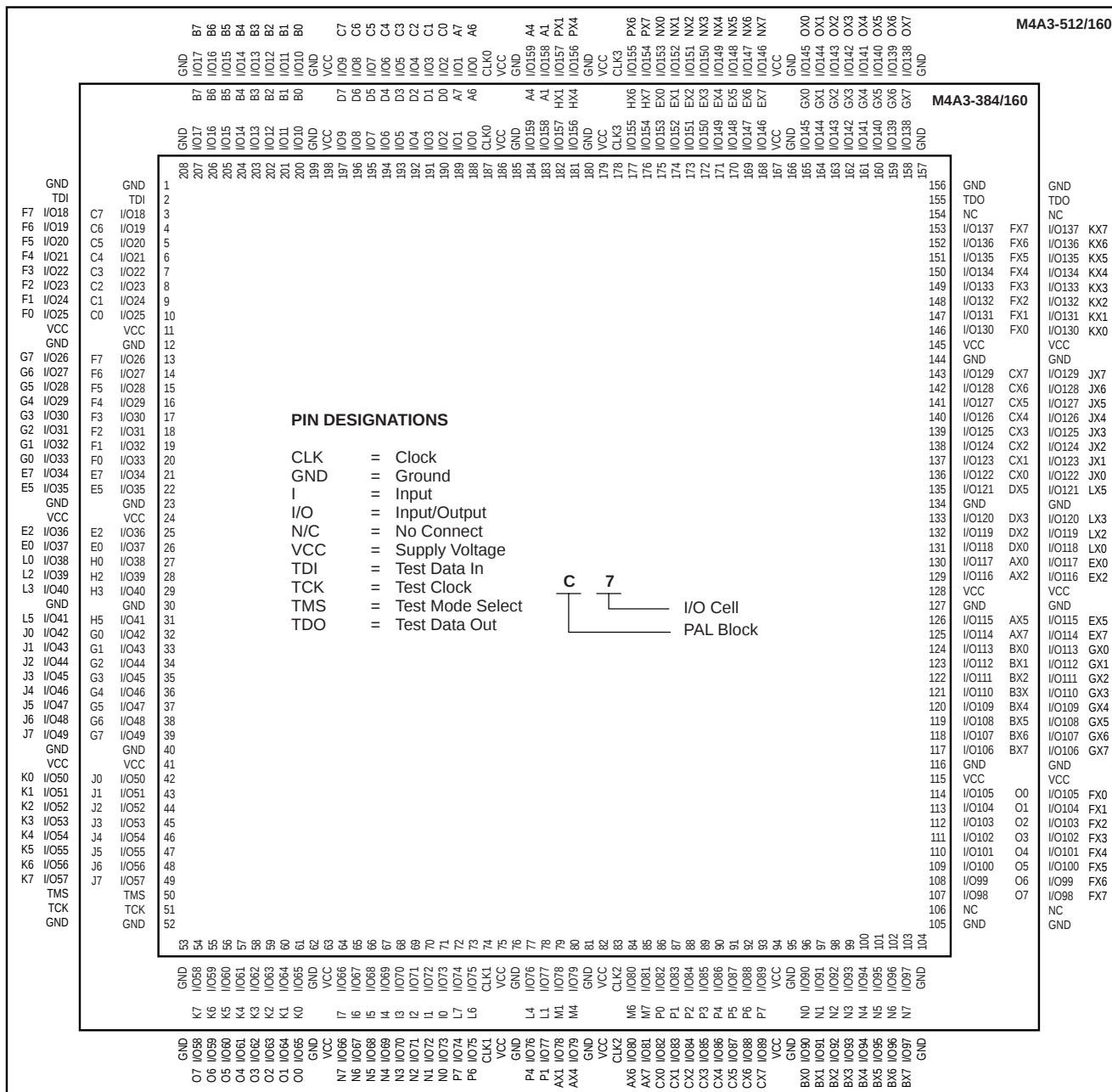


m4a3.192.96_144bga

208-PIN PQFP CONNECTION DIAGRAM (M4A3-384/160 AND M4A3-512/160)

Top View

208-Pin PQFP

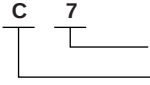


17466Ga-044

256-BALL BGA CONNECTION DIAGRAM (M4A3-256/128)

Bottom View

256-Ball BGA

	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	
A	GND	N/C	GND	I/O108 N4	I/O105 N1	GND	I/O100 M4	I/O96 M0	GND	GND	GND	GND	I/O95 L0	I/O91 L4	GND	I/O87 K0	N/C	GND	GND	GND	A
B	GND	I/O113 O6	N/C	I/O109 N5	I/O106 N2	I/O103 M7	I/O102 M6	I/O98 M2	N/C	I11	N/C	N/C	I/O93 L2	I/O89 L6	I/O88 L7	I/O85 K2	I/O83 K4	I/O82 K5	N/C	GND	B
C	I/O116 O3	N/C	VCC	TRST	I/O111 N7	I/O107 N3	I/O104 N0	I/O101 M5	I/O97 M1	N/C	I10	I/O94 L1	I/O90 L5	I/O86 K1	I/O84 K3	I/O80 K7	ENABLE	VCC	I/O78 J6	I/O74 J2	C
D	I/O120 P7	I/O117 O2	I/O112 O7	VCC	VCC	I/O110 N6	VCC	N/C	I/O99 M3	N/C	I9	I/O92 L3	N/C	VCC	I/O81 K6	VCC	VCC	I/O79 J7	I/O75 J3	I/O71 I7	D
E	I/O123 P4	I/O119 O0	I/O114 O5	TDI	PIN DESIGNATIONS CLK = Clock GND = Ground I = Input I/O = Input/Output N/C = No Connect VCC = Supply Voltage TDI = Test Data In TCK = Test Clock TMS = Test Mode Select TDO = Test Data Out TRST = Test Reset ENABLE = Program  I/O Cell PAL Block												TDO	I/O77 J5	I/O72 J0	I/O68 I4	E
F	GND	I/O122 P5	I/O118 O1	I/O115 O4													I/O76 J4	I/O73 J1	I/O69 I5	GND	F
G	I12	I/O125 P2	I/O121 P6	VCC													VCC	I/O70 I6	I/O65 I1	I8	G
H	GND	I/O127 P0	I/O126 P1	I/O124 P3													I/O67 I3	I/O66 I2	I/O64 I0	GND	H
J	N/C	N/C	N/C	I13													I7	N/C	N/C	N/C	J
K	GND	CLK3	N/C	N/C													N/C	N/C	CLK2	N/C	K
L	N/C	CLK0	N/C	N/C													N/C	N/C	CLK1	GND	L
M	N/C	N/C	N/C	I0													I6	N/C	I/O63 H0	I/O62 H1	M
N	GND	I/O0 A0	I/O2 A2	I/O3 A3													I/O60 H3	I/O61 H2	I/O59 H4	GND	N
P	I1	I/O1 A1	I/O6 A6	VCC													VCC	I/O57 H6	I/O58 H5	I5	P
R	GND	I/O5 A5	I/O9 B1	N/C													I/O51 G4	I/O54 G1	I/O56 H7	GND	R
T	I/O4 A4	I/O8 B0	I/O12 B4	TCK													TMS	I/O50 G5	I/O55 G0	N/C	T
U	I/O7 A7	I/O11 B3	I/O15 B7	VCC	VCC	I/O18 C5	VCC	I/O24 D7	I/O29 D2	I2	N/C	I/O35 E3	N/C	VCC	N/C	VCC	VCC	I/O48 G7	I/O53 G2	N/C	U
V	I/O10 B2	I/O13 B5	VCC	I/O16 C7	I/O17 C6	I/O21 C2	I/O23 C0	I/O27 D4	I/O31 D0	I3	N/C	I/O33 E1	I/O37 E5	I/O41 F1	I/O43 F3	I/O46 F6	I/O47 F7	VCC	I/O52 G3	N/C	V
W	GND	I/O14 B6	N/C	N/C	I/O19 C4	I/O22 C1	I/O25 D6	I/O28 D3	N/C	N/C	I4	N/C	I/O34 E2	I/O38 E6	I/O39 E7	I/O42 F2	I/O45 F5	N/C	I/O49 G6	GND	W
Y	GND	GND	GND	N/C	I/O20 C3	GND	I/O26 D5	I/O30 D1	GND	GND	GND	GND	I/O32 E0	I/O36 E4	GND	I/O40 F0	I/O44 F4	GND	N/C	GND	Y
	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	

17466G-045

256-BALL fpBGA CONNECTION DIAGRAM (M4A3-512/192)

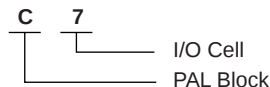
Bottom View

256-Ball fpBGA

	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	
A	I/O159 KX7	I/O181 OX5	I/O180 OX4	I/O177 OX1	I/O174 NX6	I/O172 NX4	I/O191 PX7	I/O186 PX2	I/O1 A1	I/O3 A3	CLK0	I/O17 C1	I/O21 C5	I/O23 C7	I/O10 B2	I/O12 B4	A
B	I/O157 KX5	I/O158 KX6	I/O182 OX6	I/O179 OX3	I/O175 NX7	I/O173 NX5	I/O168 NX0	I/O187 PX3	I/O0 A0	I/O5 A5	I/O7 A7	I/O18 C2	I/O8 B0	I/O11 B3	I/O13 B5	N/C	B
C	I/O155 KX3	I/O156 KX4	N/C	I/O183 OX7	I/O178 OX2	I/O170 NX2	I/O171 NX3	I/O189 PX5	I/O184 PX0	I/O6 A6	I/O20 C4	I/O22 C6	I/O15 B7	I/O14 B6	TDI	I/O39 F7	C
D	I/O150 JX6	I/O151 JX7	TDO	GND	GND	VCC	GND	VCC	GND	GND	VCC	GND	VCC	I/O9 B1	I/O38 F6	I/O37 F5	D
E	I/O148 JX4	N/C	I/O154 KX2	VCC	I/O152 KX0	I/O153 KX1	I/O190 PX6	CLK3	I/O188 PX4	I/O2 A2	I/O16 C0	N/C	GND	I/O36 F4	I/O35 F3	I/O47 G7	E
F	I/O144 JX0	I/O149 JX5	I/O147 JX3	GND	I/O146 JX2	I/O145 JX1	I/O176 OX0	I/O169 NX1	I/O185 PX1	I/O4 A4	I/O19 C3	I/O34 F2	VCC	I/O32 F0	I/O46 G6	I/O45 G5	F
G	I/O163 LX3	I/O166 LX6	I/O165 LX5	VCC	I/O164 LX4	I/O167 LX7	VCC	GND	GND	VCC	I/O33 F1	I/O44 G4	GND	I/O42 G2	I/O41 G1	I/O31 E7	G
H	I/O160 LX0	I/O162 LX2	I/O161 LX1	GND	I/O120 EX0	I/O121 EX1	GND	VCC	VCC	GND	I/O43 G3	I/O40 G0	VCC	I/O28 E4	I/O27 E3	I/O26 E2	H
J	I/O122 EX2	I/O123 EX3	I/O124 EX4	GND	I/O126 EX6	I/O125 EX5	GND	VCC	VCC	GND	I/O30 E6	I/O29 E5	GND	I/O65 L1	I/O64 L0	I/O66 L2	J
K	I/O127 EX7	I/O136 GX0	I/O137 GX1	VCC	I/O139 GX3	I/O138 GX2	VCC	GND	GND	VCC	I/O25 E1	I/O24 E0	VCC	I/O71 L7	I/O70 L6	I/O48 J0	K
L	I/O140 GX4	I/O141 GX5	I/O143 GX7	GND	I/O130 FX2	I/O142 GX6	I/O98 AX2	I/O91 P3	I/O75 N3	I/O77 N5	I/O68 L4	I/O67 L3	GND	I/O51 J3	I/O52 J4	I/O49 J1	L
M	I/O128 FX0	I/O129 FX1	I/O131 FX3	GND	I/O115 CX3	I/O113 CX1	I/O100 AX4	I/O90 P2	I/O74 N2	I/O80 O0	I/O83 O3	I/O69 L5	VCC	I/O60 K4	I/O55 J7	I/O50 J2	M
N	I/O132 FX4	I/O133 FX5	I/O135 FX7	VCC	GND	VCC	GND	VCC	GND	GND	VCC	GND	GND	TCK	I/O56 K0	I/O53 J5	N
P	I/O134 FX6	I/O109 BX5	I/O110 BX6	I/O111 BX7	I/O116 CX4	I/O114 CX2	I/O101 AX5	I/O89 P1	I/O93 P5	I/O94 P6	I/O79 N7	I/O84 O4	I/O87 O7	TMS	I/O57 K1	I/O54 J6	P
R	I/O108 BX4	I/O107 BX3	I/O104 BX0	I/O119 CX7	I/O112 CX0	I/O102 AX6	I/O99 AX3	I/O96 AX0	I/O92 P4	I/O72 N0	I/O76 N4	I/O81 O1	I/O85 O5	I/O63 K7	I/O59 K3	I/O58 K2	R
T	I/O106 BX2	I/O105 BX1	I/O118 CX6	I/O117 CX5	I/O103 AX7	CLK2	I/O97 AX1	I/O88 P0	CLK1	I/O95 P7	I/O73 N1	I/O78 N6	I/O82 O2	I/O86 O6	I/O62 K6	I/O61 K5	T
	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	

PIN DESIGNATIONS

CLK = Clock
 GND = Ground
 I = Input
 I/O = Input/Output
 N/C = No Connect
 VCC = Supply Voltage
 TDI = Test Data In
 TCK = Test Clock
 TMS = Test Mode Select
 TDO = Test Data Out



m4a3.512.192_256bga

ispMACH 4A PRODUCT ORDERING INFORMATION

ispMACH 4A Devices Commercial and Industrial - 3.3V and 5V

Lattice programmable logic products are available with several ordering options. The order number (Valid Combination) is formed by a combination of:

M4A3- 256 / 128 -7 Y C		L48	
FAMILY TYPE		= 48-pin TQFP for M4A3-32/32 or M4A3-64/32 M4A5-32/32 or M4A5-64/32	
M4A3- = ispMACH 4A Family Low Voltage Advanced Feature (3.3-V V_{CC})		OPERATING CONDITIONS	
M4A5- = ispMACH 4A Family Advanced Feature (5-V V_{CC})		C = Commercial (0°C to +70°C)	
MACROCELL DENSITY		I = Industrial (-40°C to +85°C)	
32 = 32 Macrocells 192 = 192 Macrocells		PACKAGE TYPE	
64 = 64 Macrocells 256 = 256 Macrocells		SA = Ball Grid Array (BGA)	
96 = 96 Macrocells 384 = 384 Macrocells		J = Plastic Leaded Chip Carrier (PLCC)	
128 = 128 Macrocells 512 = 512 Macrocells		JN = Lead-free Plastic Leaded Chip Carrier (PLCC)	
I/Os		V = Thin Quad Flat Pack (TQFP)	
/32 = 32 I/Os in 44-pin PLCC, 44-pin TQFP or 48-pin TQFP		VN = Lead-free Thin Quad Flat Pack (TQFP)	
/48 = 48 I/Os in 100-pin TQFP		Y = Plastic Quad Flat Pack (PQFP)	
/64 = 64 I/Os in 100-pin TQFP, 100-pin PQFP, or 100-ball caBGA		YN = Lead-free Plastic Quad Flat Pack (PQFP)	
/96 = 96 I/Os in 144-pin TQFP or 144-ball fpBGA		FA = Fine-pitch Ball Grid Array (fpBGA)	
/128 = 128 I/Os in 208-pin PQFP, 256-ball BGA or 256-ball fpBGA		FAN = Lead-free Fine-pitch Ball Grid Array (fpBGA)	
/160 = 160 I/Os in 208-pin PQFP		CA = Chip-array Ball Grid Array (caBGA)	
/192 = 192 I/Os in 256-ball BGA or 256-ball fpBGA		SPEED	
/256 = 256 I/Os in 388-ball fpBGA		-5 = 5.0 ns t_{PD}	
		-55 = 5.5 ns t_{PD}	
		-6 = 6.0 ns t_{PD}	
		-65 = 6.5 ns t_{PD}	
		-7 = 7.5 ns t_{PD}	
		-10 = 10 ns t_{PD}	
		-12 = 12 ns t_{PD}	
		-14 = 14 ns t_{PD}	

*Package obsolete, contact factory.

Conventional Packaging

3.3V Commercial Combinations			3.3V Industrial Combinations		
M4A3-32/32	-5, -7, -10	JC, VC, VC48	M4A3-32/32	-7, -10, -12	JI, VI, VI48
M4A3-64/32	-55, -7, -10	JC, VC, VC48	M4A3-64/32		JI, VI, VI48
M4A3-64/64		VC	M4A3-64/64		VI
M4A3-96/48		VC	M4A3-96/48		VI
M4A3-128/64		YC, VC, CAC	M4A3-128/64		YI, VI, CAI
M4A3-192/96	-6, -7, -10	VC, FAC	M4A3-192/96		VI, FAI
M4A3-256/128	-55, -65 ¹ , -7, -10	YC, FAC, SAC	M4A3-256/128	-10, -12	YI, FAI, SAI
M4A3-256/160	-7, -10	YC	M4A3-256/160		YI
M4A3-256/192		FAC	M4A3-256/192	-10, -12, -14	FAI
M4A3-384/160	-65, -10, -12	YC	M4A3-384/160		YI
M4A3-384/192		SAC, FAC	M4A3-384/192		FAI
M4A3-512/160	-7, -10, -12	YC	M4A3-512/160		YI
M4A3-512/192		FAC	M4A3-512/192		FAI
M4A3-512/256		FAC	M4A3-512/256		FAI

1. Use 5.5ns for new designs.

Revision History

Date	Version	Change Summary
-	K	Previous Lattice release.
August 2006	L	Updated for lead-free package options.
September 2006	M	Revised M4A3-256/160 208-pin PQFP connection diagram.